

REMARKS

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Claims 1-16 and 21-29 are currently pending. Claims 2, 3, 5 to 7, 9 and 12-16 are rejected under 35 U.S.C. §112, second paragraph. The applicants respectfully submit that claim 2, in its current amended form, overcomes this rejection. The remaining claims that depend from claim 2 also overcome this rejection for at least the same reasons.

Claims 1-12 and 14-16 are rejected under 35 U.S.C. §102(b) because the Examiner believes that they are anticipated by JP2000-77399 (hereinafter "Yamada *et al.*"). Furthermore, claim 13 is rejected under 35 U.S.C. §103 because the Examiner believes that they are rendered obvious by Yamada *et al.*

Yamada *et al.* fail to disclose the claimed inventions requirement of "at a temperature from 680° C to 750° C." Yamada *et al.*, [0029] – [0041] has the same contents as Yamada '644, column 11, line 41 to column 14, line 33, with the exceptions the following: "400°C" in column 12, line 11 of Yamada '644 is changed to "350°C" in Yamada *et al.* at column 13, line 21; in Yamada at '644, column 12, lines 15 to 18 the sentence, "If it is above 650° C, all of the organic groups will decompose, so that the moisture absorption will increase considerably and the relative dielectric constant will be raised by OH groups in the film," is changed to "If it is above 650 °C, all of the organic groups decomposes, so that the moisture absorption increases considerably and the relative dielectric constant is raised by OH groups in the film" in Yamada *et al.* at column 12, lines 23-25; between "tetraethyl orthotitanate" and "This adjusted solution" in Yamada '644, Yamada *et al.* has four sentences (see JP Yamada *et al.* at column 13, lines 39 to 48); after "tetraethyl orthotitanate" in Yamada '644, column 13, line 46, Yamada *et al.* has a phrase "in the presence of hydrochloric acid catalyst."

As mentioned above, Yamada *et al.* at column 13, lines 23 to 25 states that "If it is above 650°C, all of the organic groups decomposes, so that the moisture absorption increases considerably and the relative dielectric constant is raised by OH groups in the film." The Applicants respectfully submit that Yamada *et al.* assume and do not state the affect of temperature with certainty. This is apparent from the statement "If it is above 650°C., all of the organic groups will decompose, so that the moisture absorption will increase considerably and the relative dielectric constant will be raised by OH groups in the film." of corresponding Yamada '644, column 12, lines 15 to 18. Therefore, Yamada *et al.* teach

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away the baking temperature of "680°C to 750°C" as recited in the current pending claims.

Although the present application adopts the baking temperature of 680°C to 750°C, the baked coating film has an organic group content and exhibits increase of denseness thereof, and the resistance to hydrofluoric acid thereof is improved, (See Specification at page 23, lines 5 to 12; and at page 19, lines 13 to 23.) When the baking temperature is above 650°C., all of the organic groups will decompose, so that the moisture absorption increases considerably and a lot of OH groups are formed in the film, as stated in Yamada *et al.*, the film should have a very high etching rate against a hydrofluoric acid. However, according to the present invention, this is not true. Therefore, the subject matter of the amended claim 1 and claims that depend from it is neither anticipated nor rendered obvious from Yamada *et al.*

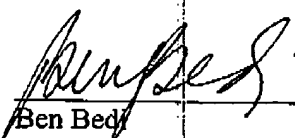
CONCLUSION

Thus, in light of the above, having responded to each and every ground of rejection, Applicants respectfully request reconsideration and allowance of the pending claims in the above-mentioned application.

Respectfully submitted,

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